

Abstract

A light emitting semiconductor package (250) has a semiconductor chip (252) with a surface with one or more light emitting devices (254) formed on or in the surface. A cap (256) is bonded to the surface of the chip (252) to encapsulate the devices (254). The cap 5 has one or more regions (258) transparent to light emitted by the light emitting devices (254). The cap has been bonded to the semiconductor chip (252) at the wafer stage prior to separation of the wafer into individual packages.